

2008 Intel Symposium on Environmentally Friendly Materials

Sponsored by iNEMI

2008英特尔环保材料研讨会
iNEMI主办

November 11-12, 2008 / Pudong, Shanghai, China
2008年11月11-12日 / 中国·上海·浦东

Agenda — Day 1
议程——第一天
November 11, 2008
2008年11月11日

- | | | | |
|-------|--|-------|--|
| 7:30 | Registration 签到 | 11:00 | iNEMI BFR-Free PCB Material Evaluation Project
iNEMI项目报告：无溴化阻燃剂线路板材料的评估
Gary Long, PCB Technology Development Engineer, Intel |
| 8:30 | Introductions 欢迎/简介
Stephen Tisdale, Packaging Manager, Intel | 11:30 | HDP User Group (HDPUG) Halogen-Free Activities
HDPUG的无卤活动
Dr. Jay Huang, Chief Process Technology Operations, Wistron Corporation |
| 8:45 | KEYNOTE: Environmental Excellence: A Call to Action
主题演讲：环境卓越 行动起来
Robin Martin, Co-General Manager, Intel Assembly & Test Manufacturing, and Managing Director, Intel Products, Shanghai | 12:00 | US EPA Flame Retardants in Printed Circuit Boards Partnership
美国环境保护署印刷电路板阻燃剂项目
Melanie Vrabel, Project Manager, US EPA |
| 9:30 | Symposium Goals / Objectives / Expected Outcome
研讨会目的、目标及预期结果
Stephen Tisdale, Packaging Manager, Intel | 12:30 | Lunch 午餐 |
| 9:45 | Driving Environmental Protection in the Electronics & Electrical Industry
推进电子电器领域的环境保护
Mr. Huang Jianzhong, Department Director, Comprehensive Resources Utilization, MIIT (Ministry of Industry and Information Technology) | 1:30 | Halogen-Free: What is It and How Did We Get Here?
什么是无卤素怎样实现无卤素
Leesha Peng, General Manager, IPC China |
| 10:15 | Break 茶歇 | 2:00 | Dell Position on BFR/CFR/PVC "Halogen-Free"
戴尔公司的无卤化的立场 (BFR/CFR/PVC的替代)
Frank Shou, Senior Environmental Consultant, Dell |
| 10:30 | Standards for the Control of Hazardous Materials
有害物质控制国内外标准化情况介绍
Mr. Xing Weibing, Deputy Chief Engineer, CESI (China Electronics Standardization Institute) | 2:30 | The Lenovo Journey to Low Halogen
联想的低卤化历程
Dr. Hongzhi Tao, Lenovo Global Desktop Environmental Team Leader |

(continued)

Agenda — Day 1 (continued)

- | | | | |
|------|---|------|---|
| 3:00 | Strategic Cooperation to Improve the Environment
改善环境需要战略合作
Dr. Haley Fu, Manager of Operations, iNEMI Asia | 5:15 | Halogen-Free Materials Expectations
对无卤素材料之期望
Terrance Richesin, Technology Development Q&R Engineer, Group Lead, Systems Materials Quality and Reliability, Intel |
| 3:30 | Break 茶歇 | 5:45 | Preview of Day 2 Activities
第二天议程预览
Stephen Tisdale, Packaging Manager, Intel |
| 3:45 | Foxconn Supplier Halogen-Free Management Overview
富士康供应商无卤管理概况
K.T. Yeh, Senior Manager, Global Procurement Division, Foxconn | 6:00 | Networking Reception 联谊招待晚宴 |
| 4:15 | Wistron's Halogen-Free Roadmap and Strategies for Implementation
纬创无卤产品规划和执行策略
Dr. Jay Huang, Chief Process Technology Operations, Wistron Corporation | | |
| 4:45 | Quanta's Halogen-Free Readiness and Initiatives
广达推动无卤素的做法
Angie Yu, Senior Manager, QSP (Quality System Planning), Quanta | | |

2008 Intel Symposium on Environmentally Friendly Materials

Sponsored by iNEMI

Agenda — Day 2

议程——第二天

November 12, 2008

2008年11月12日

- | | |
|--|---|
| <p>8:30 Welcome / Agenda Review 欢迎/议程简介
Stephen Tisdale, Packaging Manager, Intel</p> <p>8:45 KEYNOTE : Halogen Free Laminates – A Market Update, Key Properties and PCB Processability
主题演讲：无卤板材——市场、性能和PCB的工艺性
Mr. Joshua Chiang, General Manager, CCL Division, Nan Ya</p> <p>9:15 A Novel Halogen-Free Material with Low Thermal Expansion for Advanced Packaging Substrates
使用于先进封装基材的低热膨胀系数无卤素新材料
Dr. Minsu (Tim) Lee, Manager, Technical Support, Doosan</p> <p>9:45 Hitachi Halogen-Free Materials for Advanced Substrates & Printed Circuit Boards
高性能基板和印制板用Hitachi无卤材料
Mr. Tetsuro Irino, Senior Engineer, Printed Wiring Board Materials R&D Dept., Printed Wiring Board Materials Division, Electric Materials Business Sector, Hitachi Chemical Co., Ltd</p> <p>10:15 Break 茶歇</p> <p>10:30 Intel Halogen-Free Component Key Properties and Reliability Test Results
英特尔无卤器件的关键性能和可靠性试验结果
Dr. Hamid Azimi, Senior Manager, Material Development, Intel</p> | <p>11:00 Halogen-Free: A PWB Fabricator's Perspective
无卤素：线路板制造商的观点
Darren Hitchcock, Senior Field Applications Engineer, and Marie Yu, R&D Engineering Manager, Multek</p> <p>11:30 Halogen-Free in PCBs – Use, Anticipation, and Exploitation
无卤素在印刷线路板领域——应用、参与和开发
Brian Nelson, Manager, New Product Introductions, Sanmina-SCI</p> <p>12:00 Intel Halogen-Free PCB Material Evaluations and Board-Level Reliability
英特尔无卤线路板材料的评估和板级的可靠性
Gary Long, PCB Technology Development Engineer, and Ife Hsu, TD Q&R Engineer/Group Lead, Intel</p> <p>12:30 Lunch 午餐</p> <p>1:30 Impact of Halogen-Free on Connectors
无卤化对连接器的影响
David Bender, Director, Product Compliance, Tyco Electronics</p> <p>2:00 Design for Low-Halogen Green Electronics
低卤绿色电子产品设计
Dr. Tamim P. Sidiki, Innovation Program Manager, DSM Engineering Plastics</p> <p>2:30 Halogen-Free - without Constraints
无卤阻燃 无限空间
Dr. Alexandra Jacobs-Hattwig, Marketing Manager, Europe, Ticona</p> |
|--|---|

(continued)

Agenda — Day 2 (continued)

- | | | | |
|------|--|------|--|
| 3:00 | Next Generation Research & Challenges for Eco-friendly Soldering
下一代环保焊接的研发和挑战
Masato Shimamura, Senior Engineer, R&D, Senju | 5:30 | Closing Remarks 闭会总结
Stephen Tisdale, Packaging Manager, Intel |
| 3:30 | Global Halogen-Free Requirements, Progress and Solutions
全球无卤化要求、进展及应对
Dr. Sean Li, Senior Technical Manager, Restricted Substances Testing Service for E&E Products, SGS-CSTC Standards Technical Services | 5:45 | Departure 离会 |
| 4:00 | Break 茶歇 | | |
| 4:15 | PANEL DISCUSSION 嘉宾讨论
Moderator 主持 – Mr. Ife Hsu, TD Q&R Engineer, Group Lead, Intel
Substrate/PCB 基材/线路板 – Dr. Minsu (Tim) Lee, Doosan
Raw PCB Materials/Substrate 线路板原材料/基材 – Mr. Joshua Chiang, Nan Ya
Components (Packaging) 元器件 (封装) – Dr. Hamid Azimi, Intel
Connectors 连接器 – Mr. David Bender, Tyco Electronics
OEM 原始设备厂商 – Mr. Frank Shou, Dell
Consortia 协会组织 – Mr. Jim McElroy, iNEMI
ODM 原始设计厂商 – Ms. Angie Yu, Quanta
Plastics 塑料 – Dr. Tamim Sidiki, DSM Engineering Plastics | | |